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HCPL3700M
AC/DC to Logic Interface Optocoupler

Features

- AC or DC Input
- Programmable Sense Voltage
- Logic Level Compatibility
- Threshold Guaranteed Over Temperature (0°C to 70°C)
- Safety and Regulatory Approvals
  - UL1577, 5,000 VAC_{RMS} for 1 Minute
  - DIN EN/IEC60747-5-5

Applications

- Low Voltage Detection
- 5 V to 240 V AC/DC Voltage Sensing
- Relay Contact Monitor
- Current Sensing
- Microprocessor Interface
- Industrial Controls

Description

The HCPL3700M voltage/current threshold detection optocoupler consists of an AlGaAs LED connected to a threshold sensing input buffer IC which are optically coupled to a high gain darlington output. The input buffer chip is capable of controlling threshold levels over a wide range of input voltages with a single resistor. The output is TTL and CMOS compatible.

Schematics

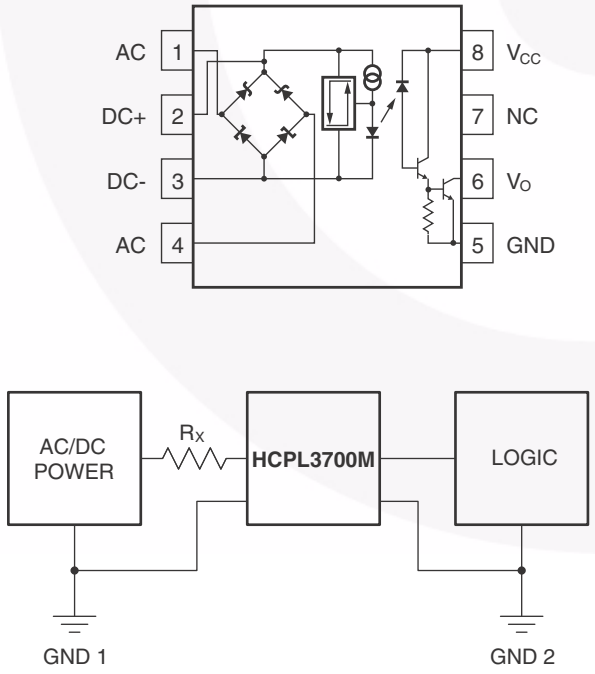


Figure 1. Schematic

Package Outlines

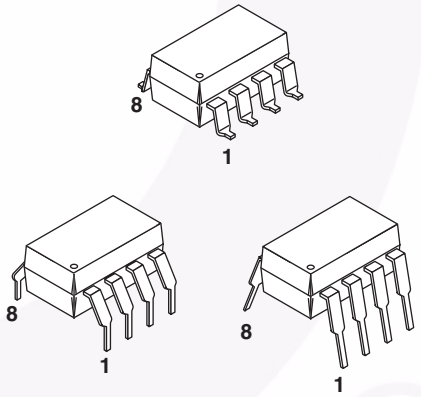


Figure 2. Package Outlines

TRUTH TABLE
(Positive Logic)

Input	Output
H	L
L	H

A 0.1µF bypass capacitor must be connected between pins 8 and 5.

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Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	< 150 V_{RMS}	I–IV
	< 300 V_{RMS}	I–IV
	< 450 V_{RMS}	I–III
	< 600 V_{RMS}	I–III
	< 1000 V_{RMS} (Option TV)	I–III
Climatic Classification		40/85/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V_{PR}	Input-to-Output Test Voltage, Method A, V_{IORM} x 1.6 = V_{PR}, Type and Sample Test with t_m = 10 s, Partial Discharge < 5 pC	2,262	V_{peak}
	Input-to-Output Test Voltage, Method B, V_{IORM} x 1.875 = V_{PR}, 100% Production Test with t_m = 1 s, Partial Discharge < 5 pC	2,651	V_{peak}
V_{IORM}	Maximum Working Insulation Voltage	1,414	V_{peak}
V_{IOTM}	Highest Allowable Over-Voltage	6,000	V_{peak}
	External Creepage	≥ 8	mm
	External Clearance	≥ 7.4	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10.16	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
T_S	Case Temperature(1)	150	°C
$I_{S,INPUT}$	Input Current(1)	25	mA
$P_{S,OUTPUT}$	Output Power (Duty Factor ≤ 2.7%)(1)	250	mW
R_{IO}	Insulation Resistance at T_S, V_{IO} = 500 V(1)	> 10^9	Ω

Note:

1. Safety limit value - maximum values allowed in the event of a failure.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. T_A = 25°C unless otherwise specified.

Symbol	Parameter		Value	Unit
T_{STG}	Storage Temperature		-40 to +125	°C
T_{OPR}	Operating Temperature		-40 to +85	°C
T_J	Junction Temperature		-40 to +125	°C
T_{SOL}	Lead Solder Temperature		260 for 10 sec	°C
P_T	Total Package Power Dissipation(2)		305	mW
EMITTER				
I_{IN}	Input Current	Average	50	mA
		Surge, 3 ms, 120 Hz Pulse Rate	140	
		Transient, 10 µs, 120 Hz Pulse Rate	500	
V_{IN}	Input Voltage (Pins 2-3)		-0.5	V
P_{IN}	Input Power Dissipation(3)		230	mW
DETECTOR				
I_O	Output Current (Average)(4)		30	mA
V_{CC}	Supply Voltage (Pins 8-5)		-0.5 to 20	V
V_O	Output Voltage (Pins 6-5)		-0.5 to 20	V
P_O	Output Power Dissipation(5)		210	mW

Notes:

2. Derate linearly above 70°C free-air temperature at a rate of 2.5 mW/°C.
3. Derate linearly above 70°C free-air temperature at a rate of 1.8 mW/°C.
4. Derate linearly above 70°C free-air temperature at a rate of 0.6 mA/°C.
5. Derate linearly above 70°C free-air temperature at a rate of 1.9 mW/°C.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	2	18	V
T_A	Ambient Operating Temperature	0	70	°C
f	Operating Frequency	0	4	kHz

Electrical Characteristics (T_A = 0°C to 70°C Unless otherwise specified)

Symbol	Parameter		Test Conditions	Min.	Typ.	Max.	Unit
I_{TH+}	Input Threshold Current		$V_{IN} = V_{TH+}$, V_{CC} = 4.5 V	1.96	2.40	3.11	mA
I_{TH-}			V_O = 0.4 V, $I_O \geq$ 4.2 mA(6)	1.00	1.20	1.62	
V_{TH+}	Input Threshold Voltage	DC (Pins 2, 3)	$V_{IN} = V_2 - V_3$ (Pins 1 & 4 Open) V_{CC} = 4.5 V, V_O = 0.4 V(6) $I_O \geq$ 4.2 mA	3.35	3.80	4.05	V
V_{TH-}			$V_{IN} = V_2 - V_3$ (Pins 1 & 4 Open) V_{CC} = 4.5 V, V_O = 2.4 V(6) $I_O \geq$ 100 µA	2.01	2.50	2.86	V
V_{TH+}		AC (Pins 1, 4)	$\lvert V_{IN} \rvert = \lvert V_1 - V_4 \rvert$ (Pins 2 & 3 Open) V_{CC} = 4.5 V, V_O = 0.4 V(6) $I_O \geq$ 4.2 mA	4.23	5.00	5.50	V
V_{TH-}			$\lvert V_{IN} \rvert = \lvert V_1 - V_4 \rvert$ (Pins 2 & 3 Open) V_{CC} = 4.5 V, V_O = 2.4 V(6) $I_O \leq$ 100 µA	2.87	3.70	4.20	V
I_{HYS}	Hysteresis		$I_{HYS} = I_{TH+} - I_{TH-}$		1.2		mA
V_{HYS}			$V_{HYS} = V_{TH+} - V_{TH-}$		1.3		V
V_{IHC1}	Input Clamp Voltage		$V_{IHC1} = V_2 - V_3$, V_3 = GND, I_{IN} = 10 mA, Pins 1 & 4 connected to Pin 3	5.4	6.3	6.6	V
V_{IHC2}			$V_{IHC2} = \lvert V_1 - V_4 \rvert$, $\lvert I_{IN} \rvert$ = 10 mA (Pins 2 & 3 Open)	6.1	7.0	7.3	V
V_{IHC3}			$V_{IHC3} = V_2 - V_3$, V_3 = GND, I_{IN} = 15 mA (Pins 1 & 4 Open)		12.5	13.4	V
V_{ILC}			$V_{ILC} = V_2 - V_3$, V_3 = GND, I_{IN} = -10 mA		-0.75		V
I_{IN}	Input Current		$V_{IN} = V_2 - V_3$ = 5.0 V (Pins 1 & 4 Open)	3.0	3.7	4.4	mA
$V_{D1,2}$	Bridge Diode Forward Voltage		I_{IN} = 3 mA		0.65		V
$V_{D3,4}$			I_{IN} = 3 mA		0.65		V
V_{OL}	Logic LOW Output Voltage		V_{CC} = 4.5 V, I_{OL} = 4.2 mA(6)		0.04	0.40	V
I_{OH}	Logic HIGH Output Current		$V_{OH} = V_{CC}$ = 18 V(6)			100	µA
I_{CCL}	Logic LOW Supply Current		$V_2 - V_3$ = 5.0 V, V_O = Open, V_{CC} = 5 V		1.0	4	mA
I_{CCH}	Logic HIGH Supply Current		V_{CC} = 18 V, V_O = Open		0.01	4	µA
C_{IN}	Input Capacitance		f = 1 MHz, V_{IN} = 0 V (Pins 2 & 3, Pins 1 & 4 Open)		50		pF

Note:

6. Logic LOW output level at pin 6 occurs when $V_{IN} \geq V_{TH+}$ and when $V_{IN} > V_{TH-}$ once V_{IN} exceeds V_{TH+}. Logic HIGH output level at pin 6 occurs when $V_{IN} \leq V_{TH-}$ and when $V_{IN} < V_{TH+}$ once decreases below V_{TH-}.

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Switching Characteristics (T_A = 25°C, V_{CC} = 5 V unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
t_{PHL}	Propagation Delay Time (to Output Low Level)	R_L = 4.7 kΩ, C_L = 30 pF(7)		6.0	15	µs
t_{PLH}	Propagation Delay Time (to Output High Level)	R_L = 4.7 kΩ, C_L = 30 pF(7)		25.0	40	µs
t_R	Output Rise Time (10–90%)	R_L = 4.7 kΩ, C_L = 30 pF		45		µs
t_F	Output Fall Time (90–10%)	R_L = 4.7 kΩ, C_L = 30 pF		0.5		µs
$\|CM_H\|$	Common Mode Transient Immunity (at Output High Level)	I_{IN} = 0 mA, R_L = 4.7 kΩ, $V_{O\ min}$ = 2.0 V, V_{CM} = 1400 V(8)(9)		4000		V/µs
$\|CM_L\|$	Common Mode Transient Immunity (at Output Low Level)	I_{IN} = 3.11 mA, R_L = 4.7 kΩ, $V_{O\ max}$ = 0.8 V, V_{CM} = 1400 V(8)(9)		600		V/µs

Isolation Characteristics (T_A = 25°C unless otherwise specified.)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{ISO}	Withstand Isolation Voltage	RH ≤ 50%, I_{I-O} ≤ 10 µA, t = 1 minute, f = 50 Hz(10)(11)	5000			VAC_{RMS}
R_{I-O}	Resistance (Input to Output)	V_{IO} = 500 V_{DC}(10)		10^{12}		Ω
C_{I-O}	Capacitance (Input to Output)	f = 1 MHz, V_{IO} = 0 V_{DC}		0.6		pF

Notes:

7. T_{PHL} propagation delay is measured from the 2.5 V level of the leading edge of a 5.0 V input pulse (1 µs rise time) to the 1.5 V level on the leading edge of the output pulse. T_{PLH} propagation delay is measured on the trailing edges of the input and output pulse. (Refer to Fig. 11)
8. Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{cm}/dt on the leading edge of the common mode pulse signal V_{CM}, to assure that the output will remain in a logic high state (i.e., V_O > 2.0 V). Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{cm}/dt on the trailing edge of the common mode pulse signal, V_{CM}, to assure that the output will remain in a logic low state (i.e., V_O < 0.8 V). Refer to Fig. 12.
9. In applications where dV_{cm}/dt may exceed 50,000 V/µs (Such as static discharge), a series resistor, R_{CC}, should be included to protect the detector chip from destructive surge currents. The recommended value for R_{CC} is 240 V per volt of allowable drop in V_{CC} (between pin 8 and V_{CC}) with a minimum value of 240 Ω.
10. Device is considered a two terminal device: Pins 1, 2, 3 and 4 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
11. The 5000 VAC_{RMS}/1 min. capability is validated by a 6000 VAC_{RMS}/1 sec. dielectric voltage withstand test.

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Typical Performance Curves

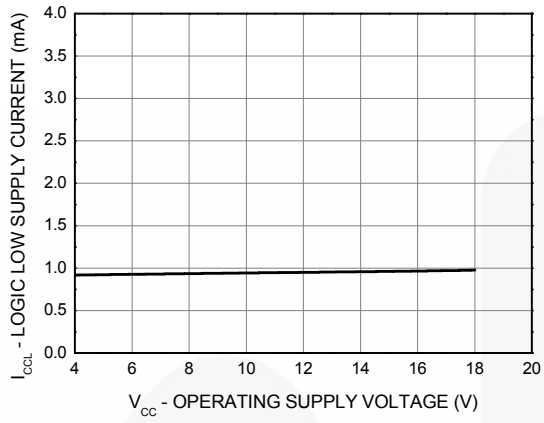


Figure 3. Logic Low Supply Current vs. Operating Supply Voltage

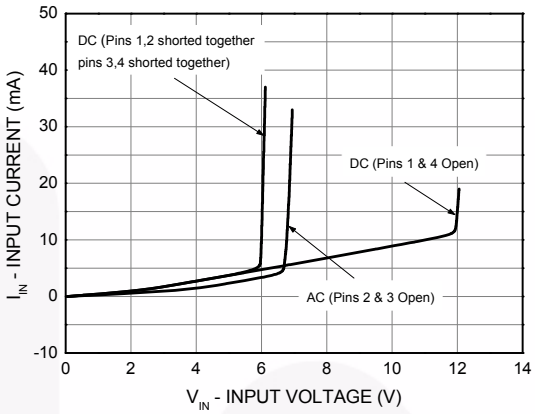


Figure 4. Input Current vs. Input Voltage

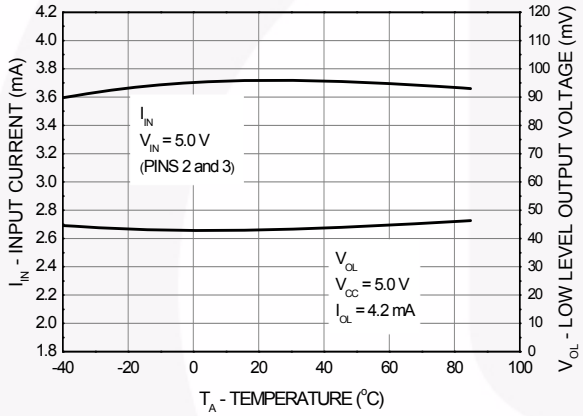


Figure 5. Input Current/Low Level Output Voltage vs. Temperature

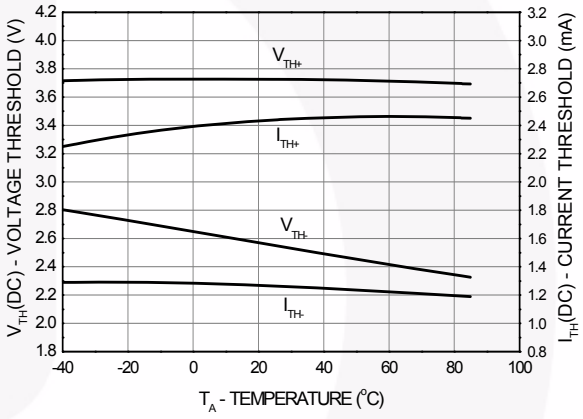


Figure 6. Current Threshold/Voltage Threshold vs. Temperature

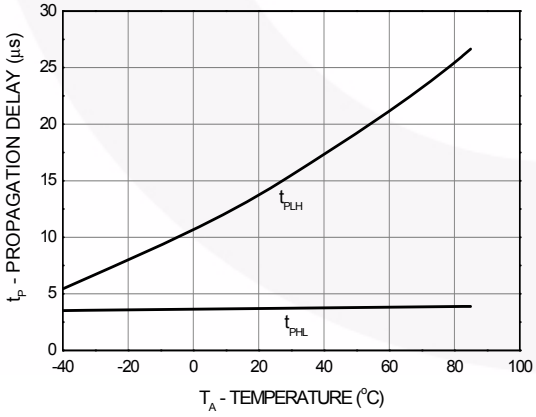


Figure 7. Propagation Delay vs. Temperature

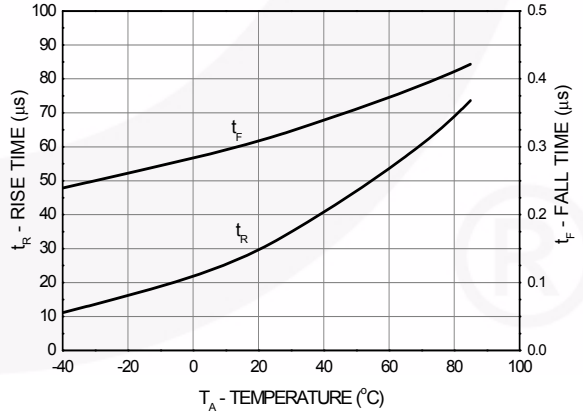


Figure 8. Rise and Fall Time vs. Temperature

Typical Performance Curves (Continued)

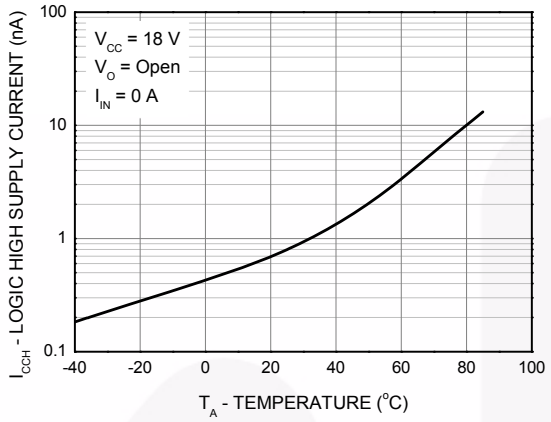


Figure 9. Logic High Supply Current vs. Temperature

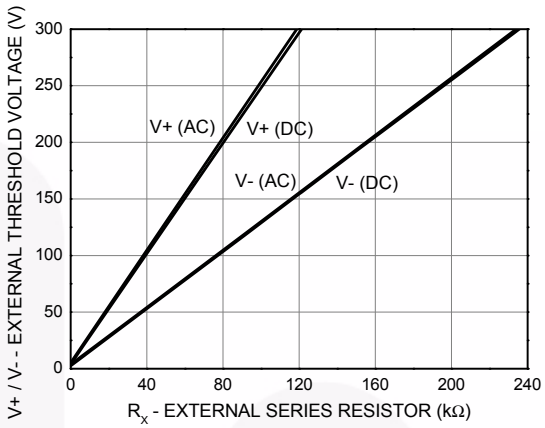
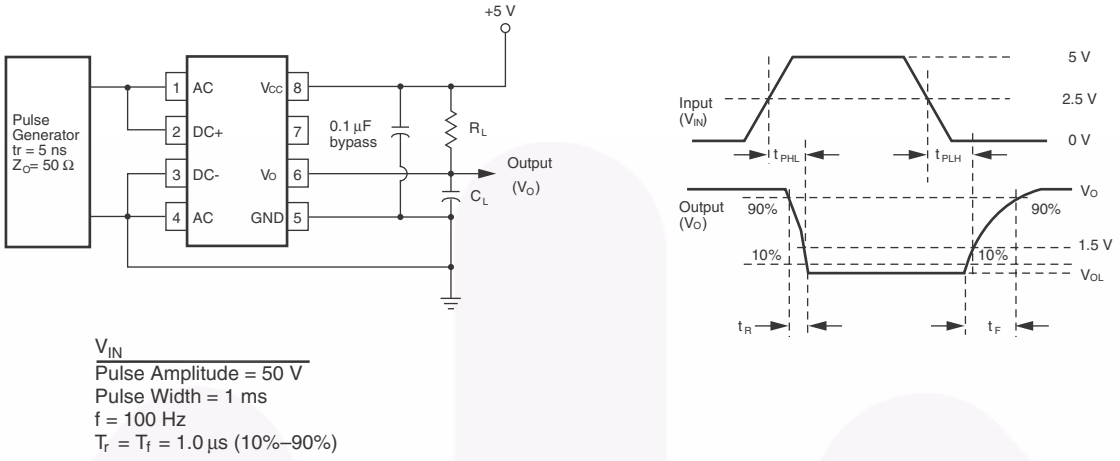


Figure 10. External Threshold Characteristics V+/V- vs. Rx

Test Circuits



V_{IN}
Pulse Amplitude = 50 V
Pulse Width = 1 ms
f = 100 Hz
$T_r = T_f = 1.0\ \mu s$ (10%–90%)

Fig. 11. Switching Test Circuit

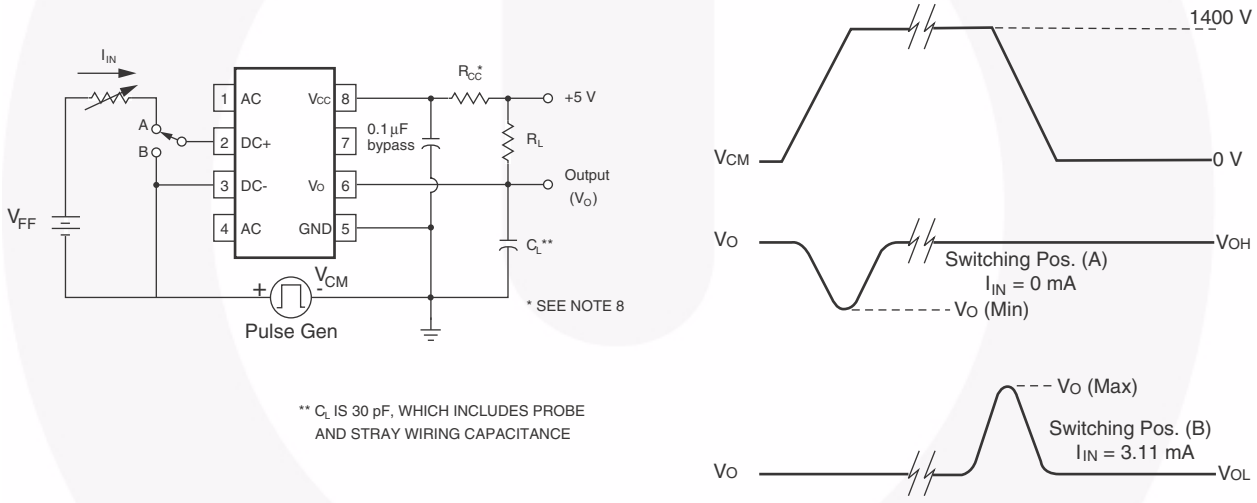
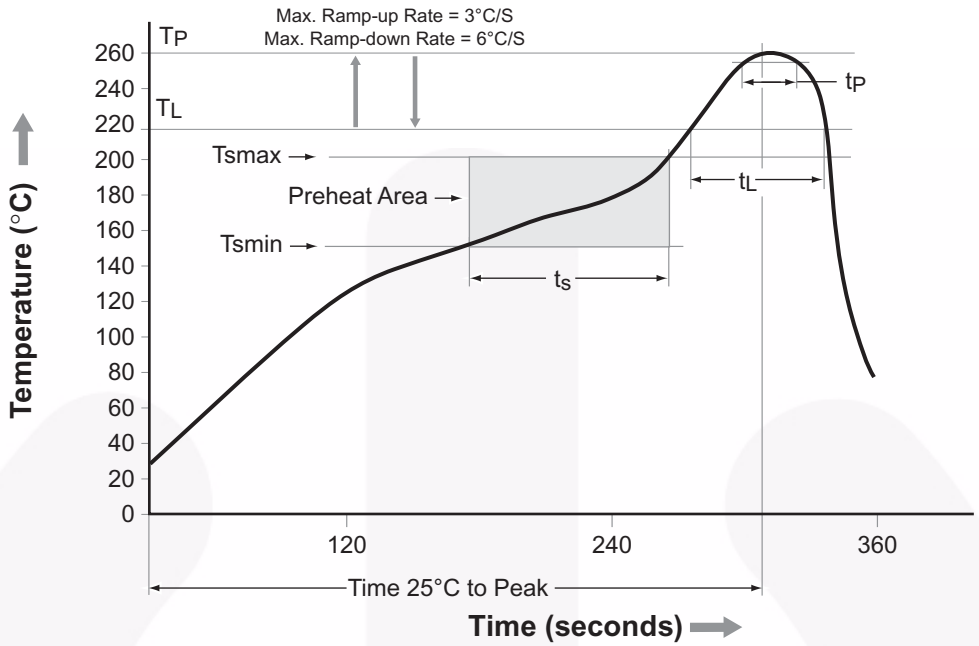


Fig. 12. Test Circuit for Common Mode Transient Immunity and Typical Waveforms

Reflow Profile



Profile Freature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (t_S) from (Tsmin to Tsmax)	60–120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60–150 seconds
Peak Body Package Temperature	260°C +0°C / –5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Figure 13. Reflow Profile

Ordering Information

Part Number	Package	Packing Method
HCPL3700M	DIP 8-Pin	Tube (50 units)
HCPL3700SM	SMT 8-Pin (Lead Bend)	Tube (50 units)
HCPL3700SDM	SMT 8-Pin (Lead Bend)	Tape and Reel (1,000 units)
HCPL3700VM	DIP 8-Pin, DIN EN/IEC60747-5-5 option	Tube (50 units)
HCPL3700SVM	SMT 8-Pin (Lead Bend), DIN EN/IEC 60747-5-5 option	Tube (50 units)
HCPL3700SDVM	SMT 8-Pin (Lead Bend), DIN EN/IEC 60747-5-5 option	Tape and Reel (1,000 units)
HCPL3700TVM	DIP 8-Pin, 0.4” Lead Spacing, DIN EN/IEC 60747-5-5 option	Tube (50 units)

Marking Information

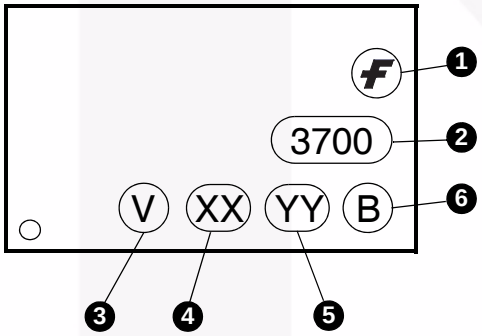
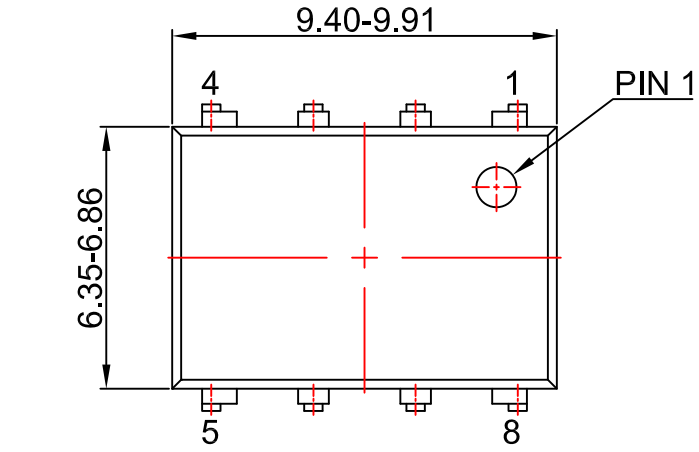
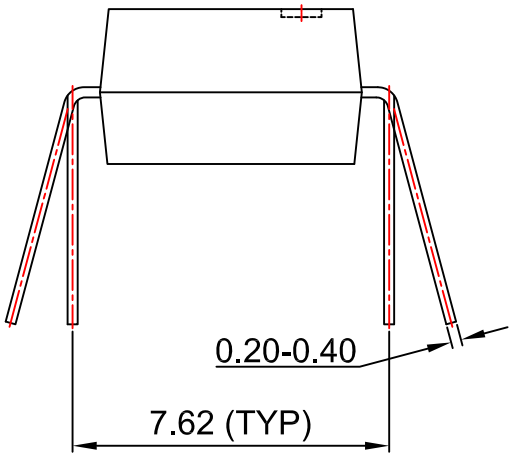
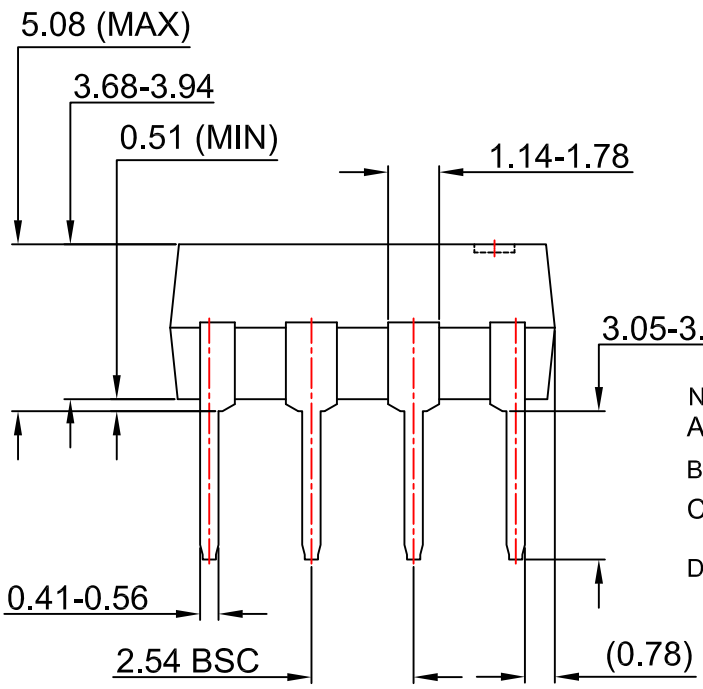


Figure 14. Top Mark

Definitions	
1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	Two Digit Year Code, e.g., ‘15’
5	Two Digit Work Week Ranging from ‘01’ to ‘53’
6	Assembly Package Code







NOTES:

A) NO STANDARD APPLIES TO THIS PACKAGE

B) ALL DIMENSIONS ARE IN MILLIMETERS.

C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

D) DRAWING FILENAME AND REVSION: MKT-N08GREV7

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